

電子材料向け多核フェノール

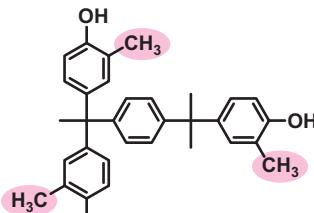
開発品

Polyphenol for electronic materials

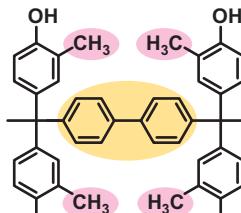
電子材料用途を志向した多様な骨格の多核フェノールを開発しています。

We develop polyphenol with diverse structures for electronic materials.

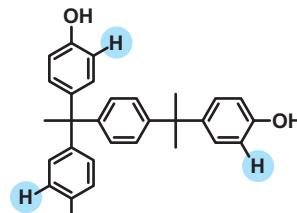
製品 Products



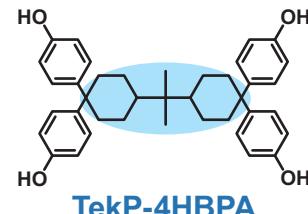
開発品



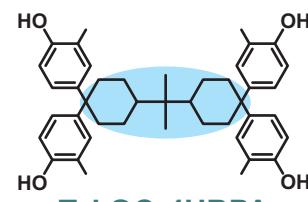
開発品



既存品



既存品



既存品

●メチル基 $-\text{CH}_3$ 導入による高溶解性・高安定性

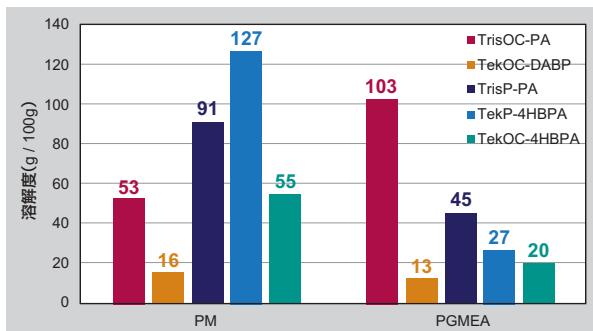
Introducing methyl groups results in high solubility and stability.

●剛直なビフェニル骨格 導入による高耐熱性

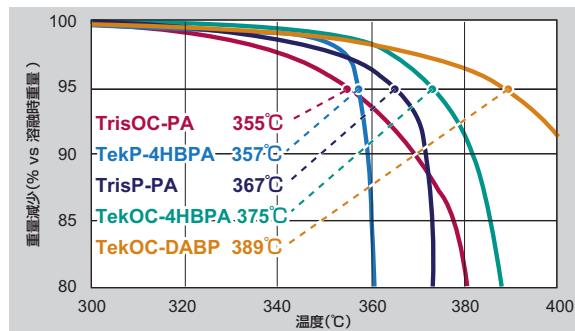
Introducing biphenyl moiety results in high heat resistant.

物性 Properties

●溶解性 Solubility



●耐熱性 Heat resistant



●スルホニルエステル溶解性 Solubility of sulfonyl esters



Test conditions

Each sulfonyl ester was filtered after dissolving in PM or PGMEA. The resulting solution was stored for 14 days under -18°C. After storage, we checked the presence of precipitation.

Polyphenols	TrisOC-PA	TekOC-DABP	TrisP-PA	TekP-4HBPA	TekOC-4HBPA
Ester conv. rate	88%	83%	89%	81%	81%
Test conc.	Results of dissolution test (PM / PGMEA)				
10%	◎ / ○	✗ / ○	✗ / ○	◎ / ○	◎ / ○
25%	◎ / ○	✗ / ○	✗ / ✗	◎ / ○	◎ / ○
40%	◎ / ○	✗ / ○	✗ / ✗	◎ / ○	◎ / ○

◎:析出なし good miscibility even at -18°C ✗:析出あり observed precipitation